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Dimensions

Chip Size	2225
L	5.588mm +/-0.381mm (0.22 in +/-0.015 in)
W	6.35mm +/-0.381mm (0.25 in +/-0.015 in)
T	1.778mm MAX (0.07 in MAX)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	25000

General Information

Series	SMD Mil PRF123
Style	SMD Chip
Description	SMD Chip, Temperature Stable
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
SCIP Number	8780dfd-a0b3-4664-b80c-18c07cfab0d1
Termination	Tin
Failure Rate	N/A
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.68 uF
Capacitance Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BX
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vms
Dissipation Factor	2.5%
Insulation Resistance	100 GOhms

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